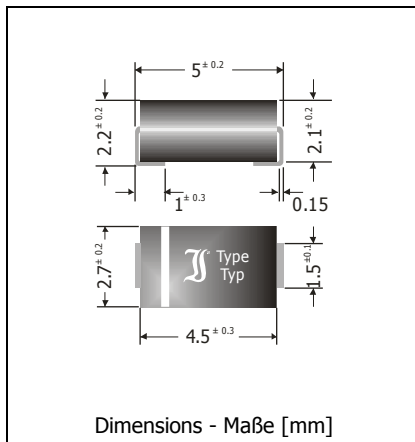


SK12 ... SK110
Surface Mount Schottky Rectifier Diodes
Schottky-Gleichrichterdioden für die Oberflächenmontage

Version 2013-05-21



Nominal current

1 A

Nennstrom

 Repetitive peak reverse voltage
 Periodische Spitzensperrspannung

20...100 V

 Plastic case
 Kunststoffgehäuse

 ~ SMA
 ~ DO-214AC

Weight approx. – Gewicht ca.

0.07g

 Plastic material has UL classification 94V-0
 Gehäusematerial UL94V-0 klassifiziert

 Standard packaging taped and reeled
 Standard Lieferform gegurtet auf Rolle
**Maximum ratings****Grenzwerte**

Type Typ	Repetitive peak reverse voltage Periodische Spitzensperrspannung V_{RRM} [V]	Surge peak reverse voltage Stoßspitzensperrspannung V_{RSM} [V]	Forward voltage Durchlass-Spannung V_F [V] ¹⁾
SK12	20	20	< 0.50
SK13	30	30	< 0.50
SK14	40	40	< 0.50
SK15	50	50	< 0.70
SK16	60	60	< 0.70
SK18	80	80	< 0.85
SK110	100	100	< 0.85

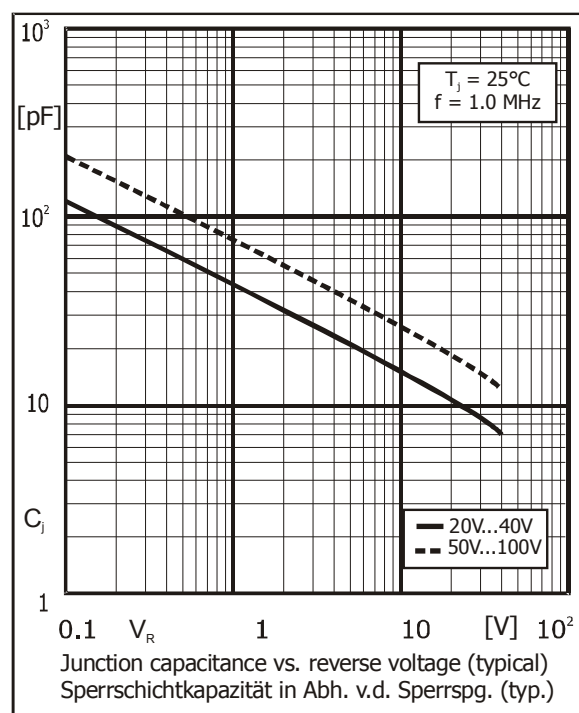
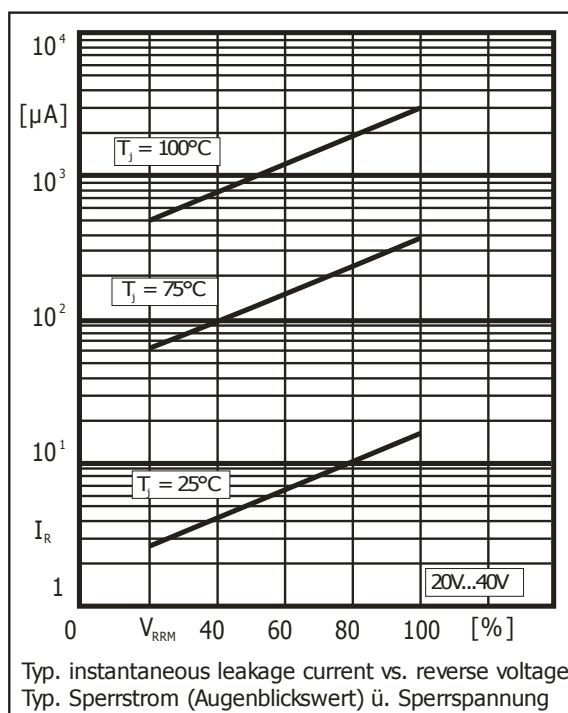
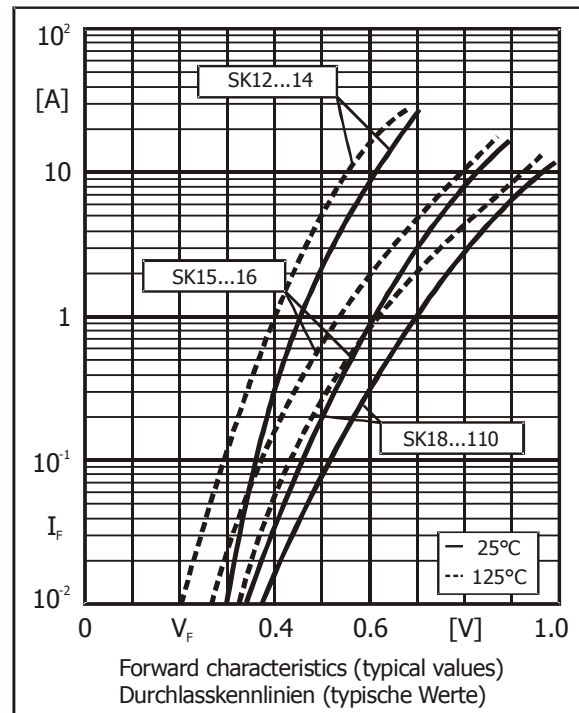
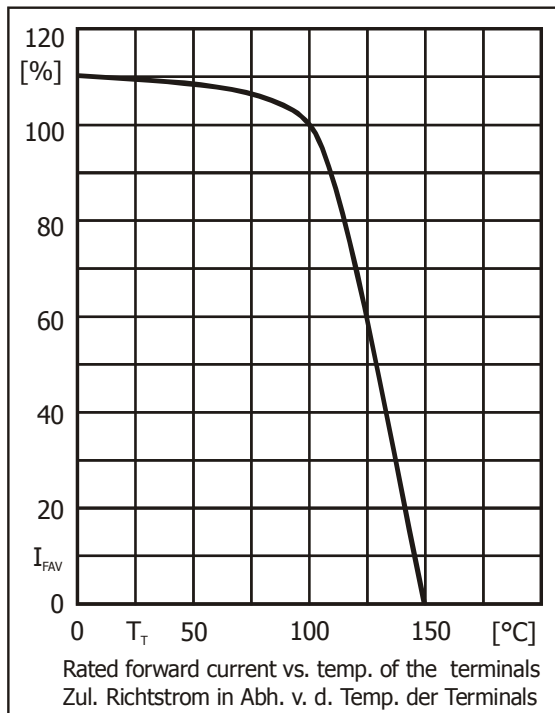
Max. average forward rectified current, R-load Dauergrenzstrom in Einwegschaltung mit R-Last	$T_T = 100^\circ\text{C}$	I_{FAV}	1 A
Repetitive peak forward current Periodischer Spitzenstrom	$f > 15\text{ Hz}$	I_{FRM}	6 A ²⁾
Peak forward surge current, 50/60 Hz half sine-wave Stoßstrom für eine 50/60 Hz Sinus-Halbwellen	$T_A = 25^\circ\text{C}$	I_{FSM}	30/33 A
Rating for fusing, $t < 10\text{ ms}$ Grenzlastintegral, $t < 10\text{ ms}$	$T_A = 25^\circ\text{C}$	i^2t	4.5 A ² s
Operating junction temperature – Sperrschichttemperatur Storage temperature – Lagerungstemperatur		T_j T_s	-50...+150°C -50...+150°C

¹ $I_F = 1\text{ A}$, $T_j = 25^\circ\text{C}$
² Max. temperature of the terminals $T_T = 100^\circ\text{C}$ – Max. Temperatur der Anschlüsse $T_T = 100^\circ\text{C}$

Characteristics

Kennwerte

Leakage current Sperrstrom	$T_j = 25^\circ\text{C}$ $T_j = 100^\circ\text{C}$	$V_R = V_{RRM}$ $V_R = V_{RRM}$	I_R I_R	$< 0.5\text{ mA}$ $< 5.0\text{ mA}$
Thermal resistance junction to ambient air Wärmewiderstand Sperrschicht – umgebende Luft			R_{thA}	$< 70\text{ K/W}^1)$
Thermal resistance junction to terminal Wärmewiderstand Sperrschicht – Anschluss			R_{thT}	$< 30\text{ K/W}$



1 Mounted on P.C. board with 25 mm² copper pads at each terminal
Montage auf Leiterplatte mit 25 mm² Kupferbelag (Löt-pad) an jedem Anschluss